



Materials Declaration Form


IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

** : Required Field*

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2018-10-12
Company Unique ID	NL 008751171B01		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	MDG MD CHAMPION	Representative Title	MDG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement	
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Legal Statement	
Supplier Acceptance *	true
Legal Declaration *	Standard
Legal Statement	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM8AL3189TCX	U05W*79KX11Z	A	959	2018-10-12
	Amount	UoM	Unit type	ST ECOPACK Grade
	350.00	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte, annealed	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFP	10x10x1.4	64	L Bend	
Comment	Package : 5W LQFP 64 10x10x1.4 1 0051434			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-27th June 2018				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	U05W*79KX112				6000001.0	1000003.0
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	5.932	mg	supplier	die	Silicon (Si)	7440-21-3		5.750	mg	969319	16429
				supplier	metallization	Aluminium (Al)	7429-90-5		0.016	mg	2697	46
				supplier	metallization	Copper (Cu)	7440-50-8		0.053	mg	8935	151
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.006	mg	1011	17
				supplier	metallization	Titanium (Ti)	7440-32-6		0.008	mg	1349	23
				supplier	Passivation	Silicon Nitride	12033-89-5		0.014	mg	2360	40
				supplier	Passivation	Silicon Oxide	7631-86-9		0.085	mg	14329	243
Lead-frame	M-011 Other inorganic materials	66.420	mg	supplier	alloy	Copper (Cu)	7440-50-8		63.896	mg	962001	182560
				supplier	alloy	Nickel (Ni)	7440-02-0		1.993	mg	30000	5693
				supplier	alloy	Silicium (Si)	7440-21-3		0.432	mg	6500	1233
				supplier	alloy	Magnesium (Mg)	7439-95-4		0.100	mg	1500	285
Die Attach	M-011 Other inorganic materials	3.703	mg	supplier	glue or soft solder	Silver (Ag)	7440-22-4		2.984	mg	806000	8527
				supplier	glue or soft solder	acrylate	65983-31-5		0.222	mg	60000	635
				supplier	glue or soft solder	Epoxy Cresol Novolak	29690-82-2		0.111	mg	30000	317
				supplier	glue or soft solder	Butadiene copolymer	68891-50-9		0.037	mg	10000	106
				supplier	glue or soft solder	poly butadiene derivative	Proprietary		0.222	mg	60000	635
				supplier	glue or soft solder	[3-(2,3-epoxypropoxy)propyl] trimethoxysilane	2530-83-8		0.074	mg	20000	212
				supplier	glue or soft solder	peroxyde de cyclohexylidènebis [tert-butyle]	3006-86-8		0.037	mg	10000	106
Wires	M-011 Other inorganic materials	1.076	mg	supplier	Bonding wire	Gold (Au)	7440-57-5		1.065	mg	990000	3042
				supplier	Bonding wire	Palladium (Pd)	7440-05-3		0.011	mg	10000	31
Encapsulation	M-011 Other inorganic materials	266.674	mg	supplier	Moulding Compound	Epoxy Resin	Proprietary		17.025	mg	63842	48643
				supplier	Moulding Compound	Phenol Resin	Proprietary		11.350	mg	42561	32429
				supplier	Moulding Compound	Silica, vitreous	6076-86-0		235.802	mg	884233	673720
				supplier	Moulding Compound	Quartz	14808-60-7		0.681	mg	2554	1946
				supplier	Moulding Compound	3-Mercaptopropyl trimethoxysilane	4420-74-0		1.135	mg	4256	3243
Finishing	M-011 Other inorganic materials	6.196	mg	supplier	Moulding Compound	Carbon black	1333-86-4		0.681	mg	2554	1946
				supplier	connections coating	Tin (Sn)	7440-31-5		6.196	mg	1000000	17703